

## CeraLink

Product Class	ss CeraLink B5804315254M052 03.03.2022 5.04							
Date								
IMDS ID if available								
Version								
Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)	
Active Part	Ceramic	3B	PLZT others*)	98 2	106390-68-5	88,7		
Inner Electrode	Heavy Metal	1C12	Cu	100	7440-50-8	9,1		
Termination	Composite	4D	Cu Glass frit (lead-boro-silicate)	93	7440-50-8	2		
	Heavy Metal	1C14	Ni	100	7440-02-0	0,1		
	Heavy Metal	1C8	Sn	100	7440-31-5	0,1		
					Sum of total	100		
sizes [ mm] 5.7x5x1.4	weight range [g] material numbers 0.26 B58043I5254M052							
Not part of a Product								
Contact	Ronner Christoph	Important remarks:						
Division	PPD Q QM	M			The designation limit is 0.4% as defined by IEO 00474 (IEO DAO 04000). T			
Address	8530 Deutschlandsberg	q, AUSTRIA		1) The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise				
	Tel:	mailto:	regulated.				5 4	
'	+43 3462 800 2139 e or prohibited substance	functional.ppd-epqm.db@t es acc. GADSL	dk-electronics.tdk.com	herein. We expressly point out that all values and statements contained herein are based on our				
**) typical mass percen	tage of substance			best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE.				
			ble means that products are comp riction of the use of certain hazard				Directive 2011/65/EU of	
RoHS - Exemptions for	or the Product Class / F	Product according to An	nex III: ( 🗹 valid 🛛 not valid )					
□ Exemption 6 (b): L   □ Exemption 6 (c): C   □ Exemption 7 (a): L   ☑ Exemption 7 (c)-1: E   ☑ Exemption 7 (c)-1: I	Lead as an alloying element Copper alloy containing up to Lead in high melting tempera Electrical and electronic corr Lead in dielectric ceramic in	in aluminium containing up to o 4 % lead by weight; ature type solder (i.e. lead-ba oponents containing lead in a capacitors for a rated voltage	ess and in galvanized steel containing to 0,0,4 % lead by weight; sed alloys containing 85 % by weight c glass or ceramic other than dielectric c of 125 V AC or 250 V DC or higher; o of less than 125 V AC or 250 V DC;	or more lead);		a glass or ceramic matrix corr	ipound;	
	ead in solders to complete an above		between semiconductor die and carrie	r within integrated circuit	t Flip Chip packages;			